



YAREN
TECHNOLOGY

IRF640
Power MOSFET

18Amps, 200 Volts N-CHANNEL POWER MOSFET

■ DESCRIPTION

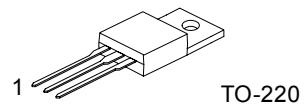
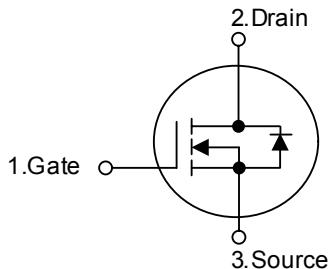
The YR IRF640 are N-Channel enhancement mode power field effect transistors (MOSFET) which are produced using YR's proprietary, planar stripe, DMOS technology.

These devices are suited for high efficiency switch mode power supply. To minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode the advanced technology has been especially tailored.

■ FEATURES

- * $R_{DS(ON)} = 0.18 \Omega$ @ $V_{GS} = 10 V$
- * Ultra low gate charge (typical 42 nC)
- * Low reverse transfer capacitance ($C_{RSS} =$ typical 25 pF)
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

■ SYMBOL



TO-220

*Pb-free plating product number: IRF640

■ ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	200	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	18	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	11	A
I_{DM}	Pulsed Drain Current ¹	72	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	125	W
	Linear Derating Factor	0.39	W/ $^\circ C$
E_{AS}	Single Pulse Avalanche Energy ²	259	mJ
I_{AR}	Avalanche Current	18	A
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

■ THERMAL DATA

Symbol	Parameter	Value	Unit
R_{thj-c}	Thermal Resistance Junction-case	Max. 1.0	$^\circ C/W$
R_{thj-a}	Thermal Resistance Junction-ambient	Max. 62	$^\circ C/W$

■ ELECTRICAL CHARACTERISTICS $T_C = 25^\circ C$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	200	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D = 9.0A$		--	0.18	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	4	V
g_{fs}	Forward Transconductance	$V_{DS}=40V, I_D=9.0A$		13.5	-	S
I_{DSS}	Drain-Source Leakage Current ($T_j=25^\circ C$)	$V_{DS}=200V, V_{GS}=0V$	-	-	25	μA
	Drain-Source Leakage Current ($T_j=125^\circ C$)	$V_{DS}=160V, V_{GS}=0V$	-	-	250	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 20V$	-	-	± 100	nA
Q_g	Total Gate Charge ³	$I_D=18A$	-	25	45	nC
Q_{gs}	Gate-Source Charge		-	4	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge		-	14	-	nC
$t_{d(on)}$	Turn-on Delay Time ³	$V_{DD}=100V$ $I_D=9.0A$	-	10	-	ns
t_r	Rise Time		-	29	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	32	-	ns
t_f	Fall Time		-	24	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$ $V_{DS}=25V$	-	630	1010	pF
C_{oss}	Output Capacitance		-	210	-	pF
C_{rss}	Reverse Transfer Capacitance		-	65	-	pF
R_g	Gate Resistance	$f=1.0MHz$	-	1.6	2.4	Ω

IRF640

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ³	$T_j=25^\circ C$, $I_s=18A$, $V_{GS}=0V$	-	-	1.5	V
t_{rr}	Reverse Recovery Time ³	$I_s=9A$, $V_{GS}=0V$,	-	225	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu s$	-	2.2	-	μC

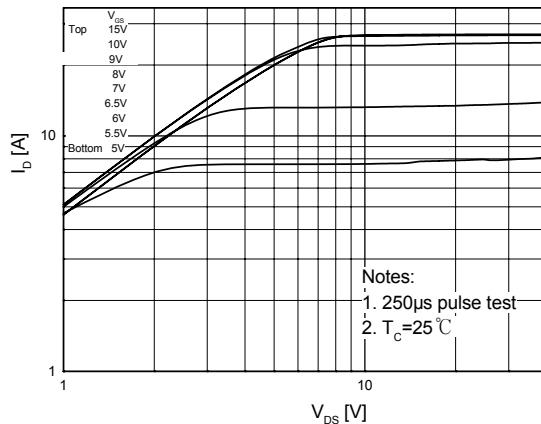
Notes:

1.Pulse width limited by Max. junction temperature.

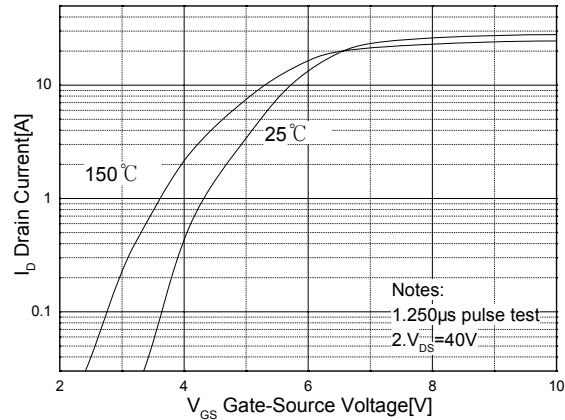
2.Starting $T_j=25^\circ C$, $V_{DD}=50V$, $L=1mH$, $R_G=25\Omega$

3.Pulse test

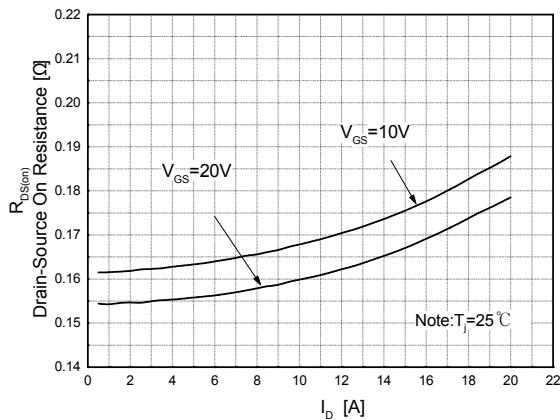
On-Region Characteristics



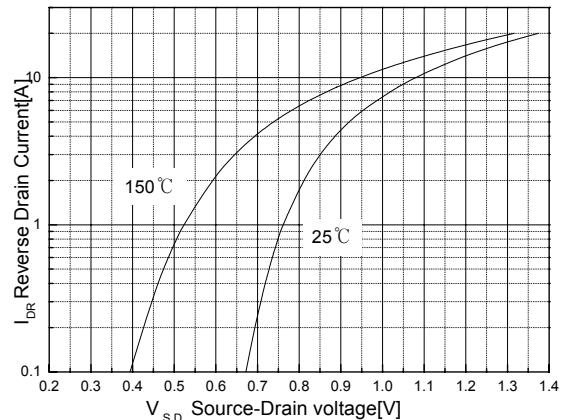
Transfer Characteristics



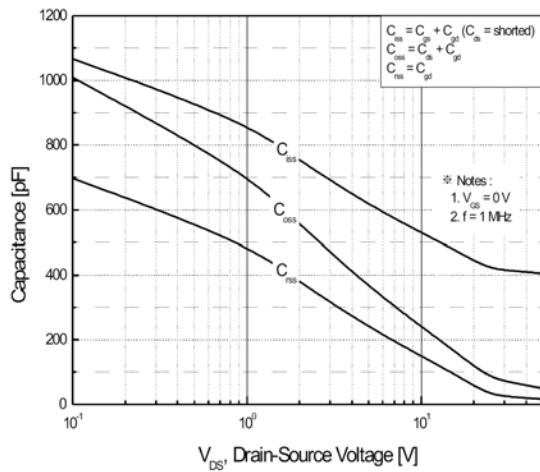
On-Resistance Variation vs. Drain Current and Gate Voltage



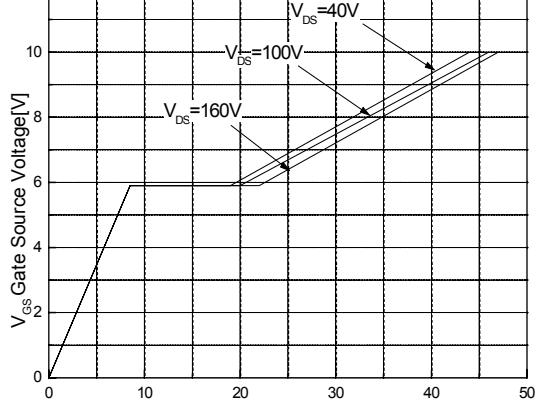
Body Diode Forward Voltage Variation vs. Source Current and Temperature



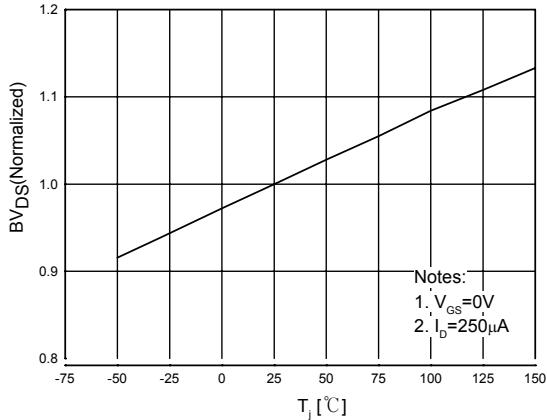
Capacitance Characteristics



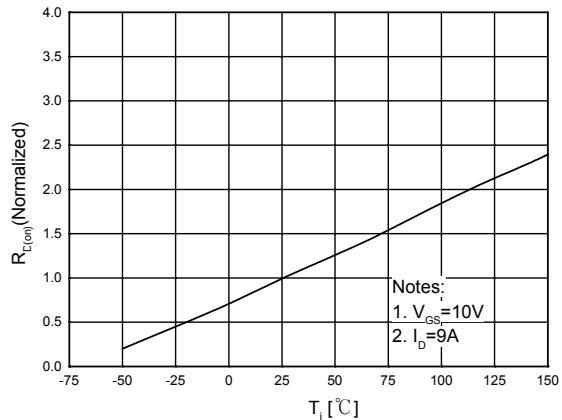
Gate Charge Characteristics



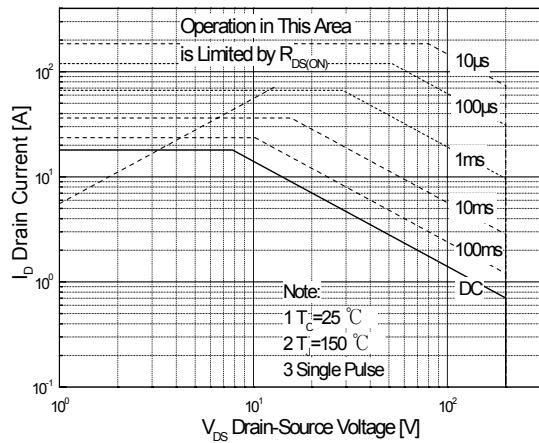
Breakdown Voltage Variation vs. Temperature



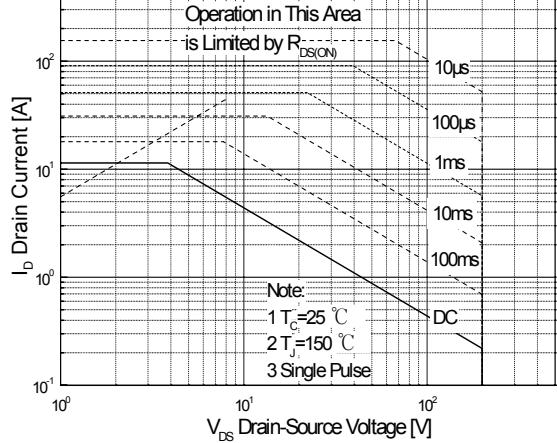
On-Resistance Variation vs. Temperature



Maximum Safe Operating Area For JCS640C



Maximum Safe Operating Area For JCS640F



Maximum Drain Current vs. Case Temperature

